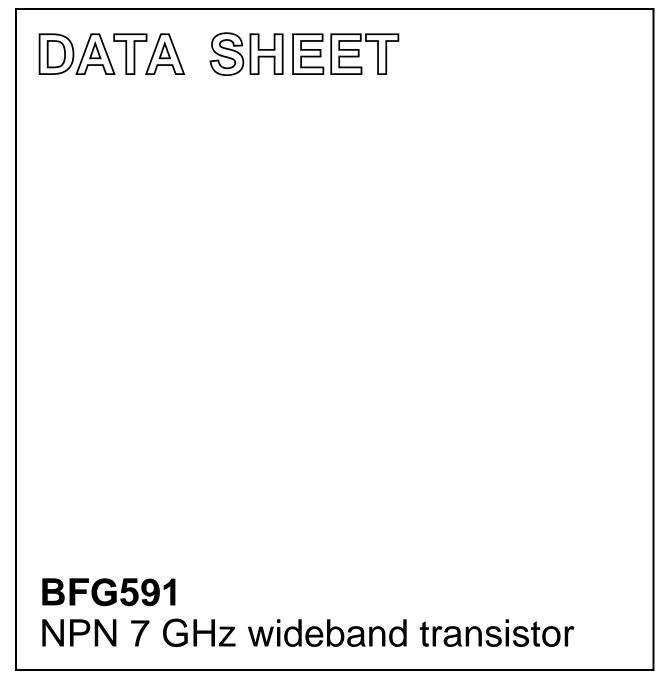
DISCRETE SEMICONDUCTORS



Product specification Supersedes data of November 1992 1995 Sep 04



FEATURES

- High power gain
- Low noise figure
- High transition frequency
- Gold metallization ensures excellent reliability.

APPLICATIONS

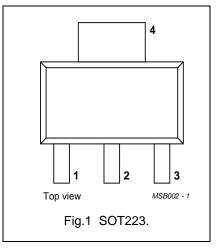
Intended for applications in the GHz range such as MATV or CATV amplifiers and RF communications subscriber equipment.

DESCRIPTION

NPN silicon planar epitaxial transistor in a plastic, 4-pin SOT223 package.

PINNING

PIN	DESCRIPTION		
1	emitter		
2	base		
3	emitter		
4	collector		



QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	_	_	20	V
V _{CEO}	collector-emitter voltage	open base	-	-	15	V
I _C	collector current (DC)		-	-	200	mA
P _{tot}	total power dissipation	up to $T_s = 80 \ ^{\circ}C$; note 1	-	-	2	W
h _{FE}	DC current gain	I _C = 70 mA; V _{CE} = 8 V	60	90	250	
C _{re}	feedback capacitance	$I_{C} = I_{c} = 0$; $V_{CE} = 12$ V; f = 1 MHz	-	0.7	-	pF
f _T	transition frequency	I_{C} = 70 mA; V_{CE} = 12 V; f = 1 GHz	-	7	-	GHz
G _{UM}	maximum unilateral power gain	I _C = 70 mA; V _{CE} = 12 V; f = 900 MHz; T _{amb} = 25 °C	-	13	-	dB
s ₂₁ ²	insertion power gain	I _C = 70 mA; V _{CE} = 12 V; f = 900 MHz; T _{amb} = 25 °C	-	12	-	dB

Note

1. T_s is the temperature at the soldering point of the collector pin.

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LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	-	20	V
V _{CEO}	collector-emitter voltage	open base	-	15	V
V _{EBO}	emitter-base voltage	open collector	-	3	V
I _C	collector current (DC)		-	200	mA
P _{tot}	total power dissipation	up to T _s = 80 °C; note 1	-	2	W
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		-	150	°C

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-s}	thermal resistance from junction to soldering point	note 1	35	K/W

Note to the Limiting values and Thermal characteristics

1. T_s is the temperature at the soldering point of the collector pin.

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CHARACTERISTICS

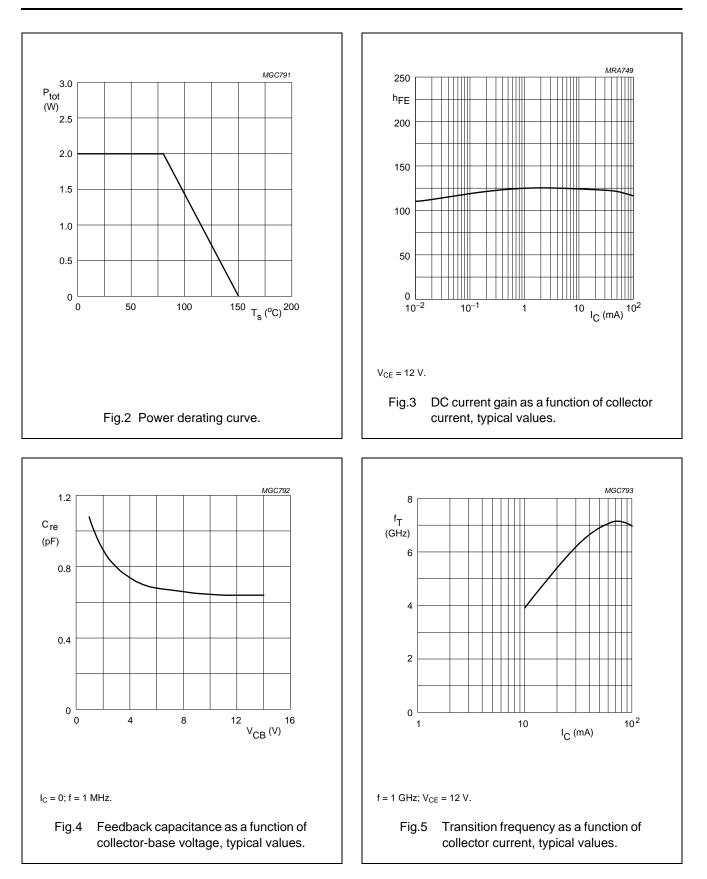
 $T_i = 25 \ ^{\circ}C$ (unless otherwise specified).

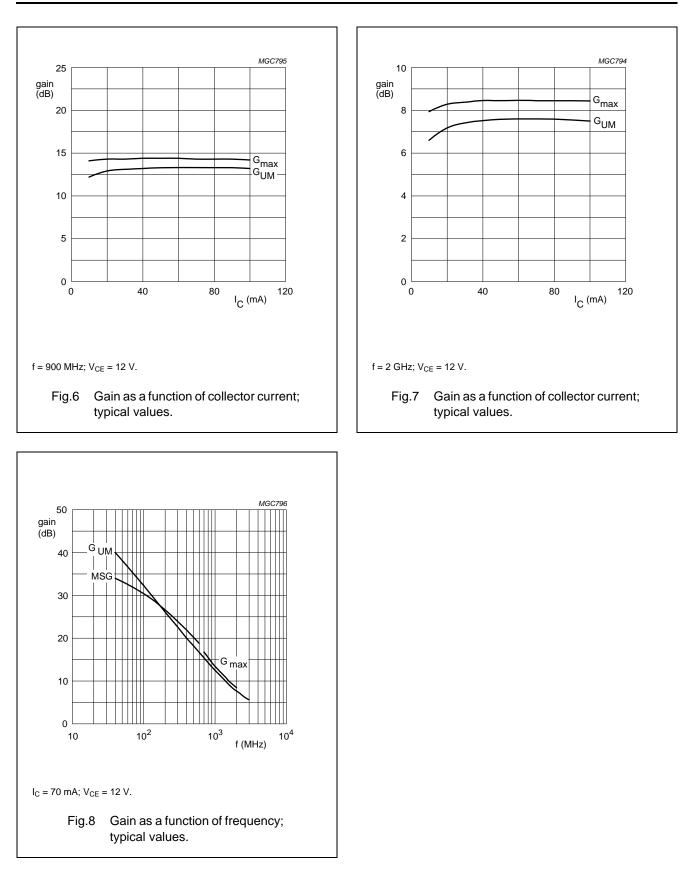
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _{(BR)CBO}	collector-base breakdown voltage	$I_{\rm C} = 0.1 \text{ mA}; I_{\rm E} = 0$	20	-	-	V
V _{(BR)CES}	collector-emitter breakdown voltage	$I_{C} = 10 \text{ mA}; I_{B} = 0$	15	-	-	V
V _{(BR)EBO}	emitter-base breakdown voltage	$I_{E} = 0.1 \text{ mA}; I_{C} = 0$	3	-	-	V
I _{CBO}	collector-base leakage current	I _E = 0; V _{CB} = 10 V	-	-	100	nA
h _{FE}	DC current gain	I _C = 70 mA; V _{CE} = 8 V	60	90	250	
C _{re}	feedback capacitance	$I_B = I_b = 0; V_{CE} = 12 V;$ f = 1 MHz	-	0.7	-	pF
f _T	transition frequency	I _C = 70 mA; V _{CE} = 12 V; f = 1 GHz	-	7	-	GHz
G _{UM}	maximum unilateral power gain; note 1	I _C = 70 mA; V _{CE} = 12 V; f = 900 MHz; T _{amb} = 25 °C	-	13	-	dB
		I _C = 70 mA; V _{CE} = 12 V; f = 2 GHz; T _{amb} = 25 °C	-	7.5	-	dB
s ₂₁ ²	insertion power gain	I _C = 70 mA; V _{CE} = 12 V; f = 1 GHz; T _{amb} = 25 °C	-	12	-	dB
Vo	output voltage	note 2	-	700	-	mV

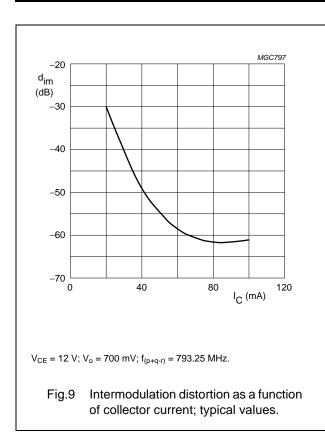
Notes

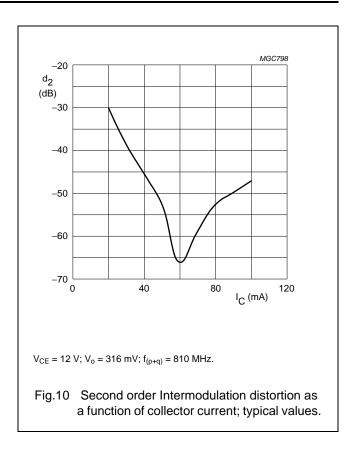
1. G_{UM} is the maximum unilateral power gain, assuming s_{12} is zero. $G_{UM} = 10 \log \frac{|s_{21}|^2}{(1-|s_{11}|^2)(1-|s_{22}|^2)} dB$.

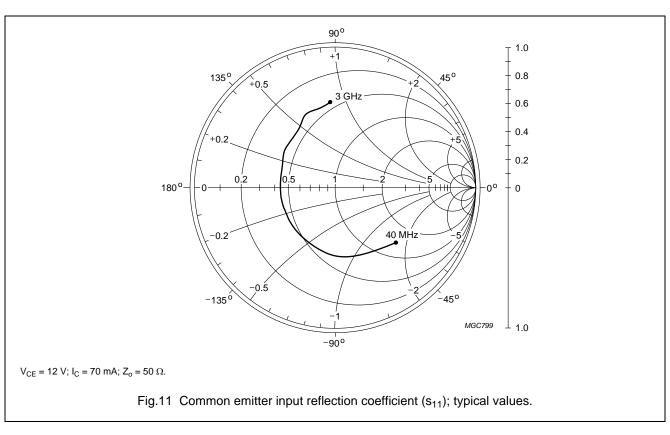
2. $d_{im} = 60 \text{ dB} (\text{DIN45004B});$ $V_p = V_{o;} V_q = V_o - 6 \text{ dB}; V_r = V_o - 6 \text{ dB};$ $f_p = 795.25 \text{ MHz}; f_q = 803.25 \text{ MHz}; f_r = 803.25 \text{ MHz};$ measured at $f_{(p+q-r)} = 793.25 \text{ MHz}.$

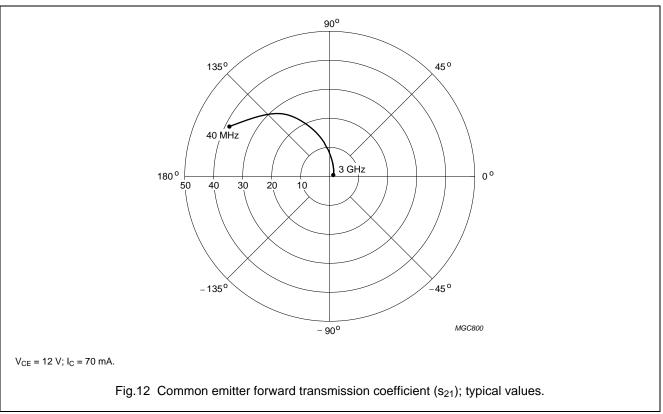


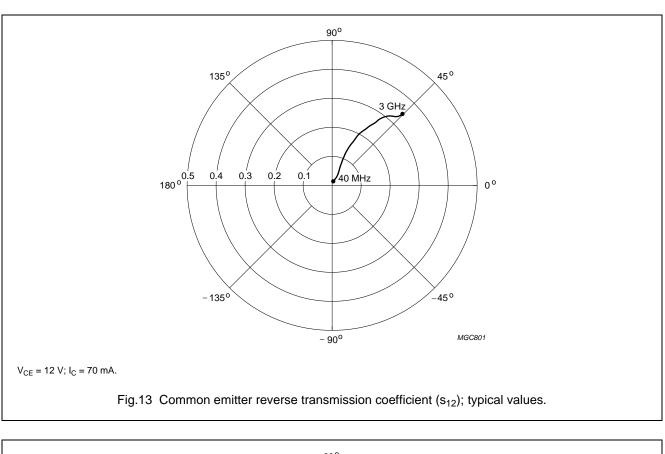


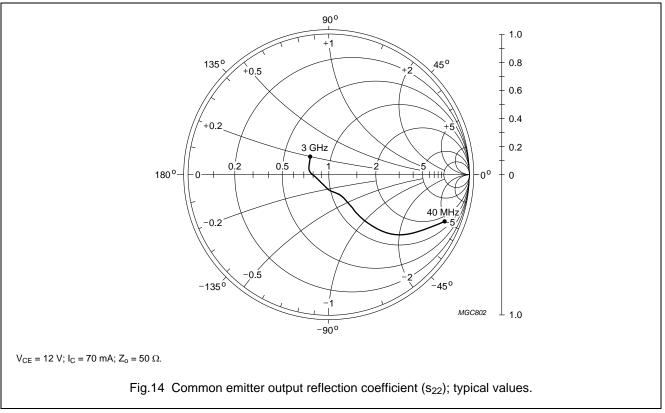






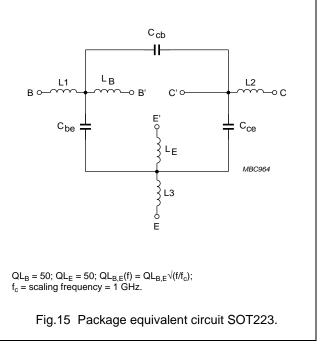






SEQUENCE No. PARAMETER VALUE UNIT IS 1 1.341 fA 2 ΒF 123.5 NF 3 .988 m 4 VAF 75.85 V 5 IKF A 9.656 6 ISE 232.2 fA 7 NE 2.134 _ 8 BR 10.22 _ NR 9 1.016 ____ 10 VAR 1.992 V 11 IKR 294.1 mΑ 12 ISC 211.0 aА 13 NC 997.2 14 RB 5.00 Ω 15 IRB μA 1.000 RBM 5.00 16 Ω 17 RE 1.275 Ω RC 920.6 18 mΩ 19 (1) XTB 0.000 20 (1) EG 1.110 ΕV 21 (1) XTI 3.000 _ 22 CJE 3.821 pF 23 VJE 600.0 m٧ 24 MJE 348.5 m 25 TF 13.60 ps 26 XTF 71.73 27 VTF 10.28 V 28 ITF 1.929 А PTF 29 0.000 deg CJC 1.409 30 pF 31 VJC 219.4 mV 32 MJC 166.5 m 33 XCJ 2.340 m 34 TR 543.7 ns 35 (1) CJS 0.000 F 36 (1) VJS 750.0 mV 37 (1) MJS 0.000 38 FC 733.2 m

SPICE parameters for the BFG591 crystal



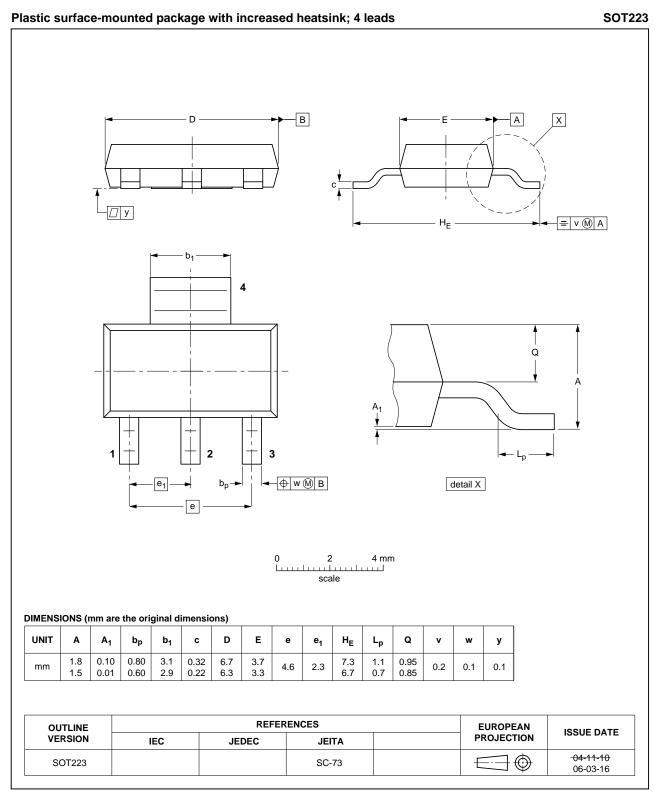
List of components (see Fig.15)

DESIGNATION	VALUE	UNIT
C _{be}	182	fF
C _{cb}	16	fF
C _{ce}	249	fF
L1	0.025	nH
L2	1.19	nH
L3	0.60	nH
L _B	1.50	nH
L _E	0.50	nH

Note

1. These parameters have not been extracted, the default values are shown.

PACKAGE OUTLINE



BFG591

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

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